

IN52/SN48 SOLDER ALLOY

FEATURES

- Good Thermal Fatigue Resistance
- Recommended For Thick and Thin Film Gold
- Low Temperature 118°C

DESCRIPTION

In52/Sn48 is typically used for die attach in microwave devices. It is also used in cryogenic applications where pliable seals and good electrical conductivity are necessary. In52/Sn48 meets ASTM as well as IPC-J-STD-006.

IMPURITY LEVELS TO IPC-J-STD-006 IN PERCENT

Impurity Levels To IPC-J-STD-006 In Percent				
Al: 0.005	Pb: 0.20	Cd: 0.002	Fe: 0.02	Sb: 0.50
As: 0.03	Bi: 0.10	Cu: 0.08	Ni: 0.01	Zn: 0.003

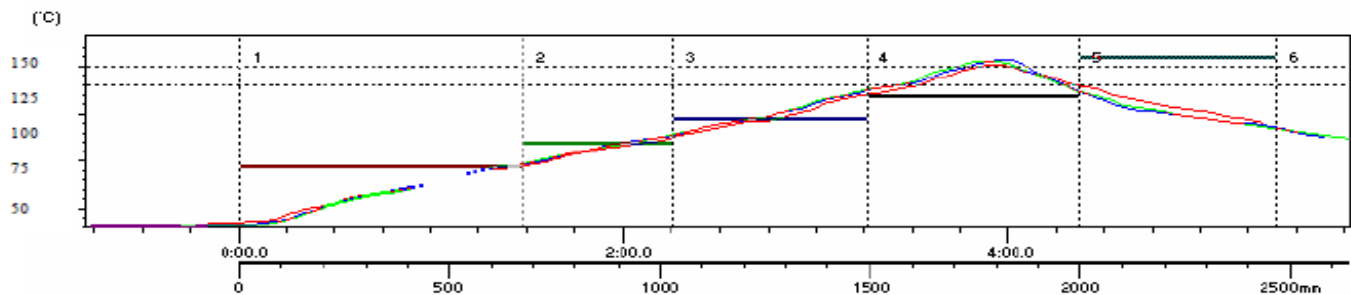
HANDLING & STORAGE

Indium/Tin alloys should be stored in a dry temperature controlled room or in an inert atmosphere, as Indium alloys will corrode in humidity. Any device used in high humidity applications, or having potential exposure to condensation, should be conformal-coated.

FLUX COMPATIBILITY

Indium/Tin alloys are compatible with most electronic grade fluxes. Indium alloys should never be used with high-halide fluxes. Indium forms a mono-halide compound very quickly.

REFLOW DATA



Rate of Rise 2- 3°C/sec max	Preheat Ramp to 75°C	Directly to Reflow 150°C ± 5°C	Time Above 118°C	Profile Length	Cool Down <-4°C
	</- 90 secs		45-60 secs	3 ½ - 4 minutes	

CLEANING

Refer to data sheets provided by flux manufacturer.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

Document Rev # NF1
Page 1 of 1

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